

AN11648

LPC18Sxx/43Sxx Secure Boot from QSPI Device

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Application note

Document information

Info	Content
Keywords	LPC18Sxx, LPC43Sxx, AES, Secure boot, LPCScript
Abstract	The application note describes how to secure boot from an encrypted image in a QSPI flash device.



Revision history

Rev	Date	Description
1.1	20150224	Initial version

Contact information

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1. Introduction

The LPC18Sxx/43Sxx devices are ARM Cortex-M4 based microcontrollers for embedded applications, which include an ARM Cortex-M0 coprocessor, up to 264 kB of SRAM, security features with AES engine, advanced configurable peripherals such as the State Configurable Timer/PWM (SCTimer/PWM) and the Serial General-Purpose I/O (SGPIO) interface, two High-speed USB controllers, Ethernet, LCD, an external memory controller, and multiple digital and analog peripherals.

The AES engine is used for encryption and decryption of the boot image and data with DMA support and is programmable via ROM-based APIs. Two One-Time Programmable (OTP) memory banks (128 bit each) are available for AES key storage.

All LPC18Sxx/43Sxx parts can boot from a secure (encrypted) image. For parts with on-chip flash, the ISP mode must be enabled to select an external boot source with the encrypted image. The boot source can be an external device, such as a QSPI flash or USB.

An encrypted image is created from a plain image using a 128 bit AES key. A secure (encrypted) image is always preceded by an encrypted header. Cypher-based Message Authentication Code (CMAC) authentication is performed on the boot image. The CMAC algorithm is used to calculate a 128 bit hash tag, which is used for image authentication. The tag is stored in the header. At boot time the tag is recalculated. Authentication passes when the calculated tag is equal to the received tag in the image header.

The encrypted image required for secure boot is created with a utility called LPCScript. LPCScript is a fast flash and security programming tool for the LPC18xx/43xx family of microcontrollers.

Note: The default AES key in the MCU is all 0. During debug, it is recommended to use this default key. Do not program 0s into OTP memory. Programming 0s will block JTAG access for flashless parts.

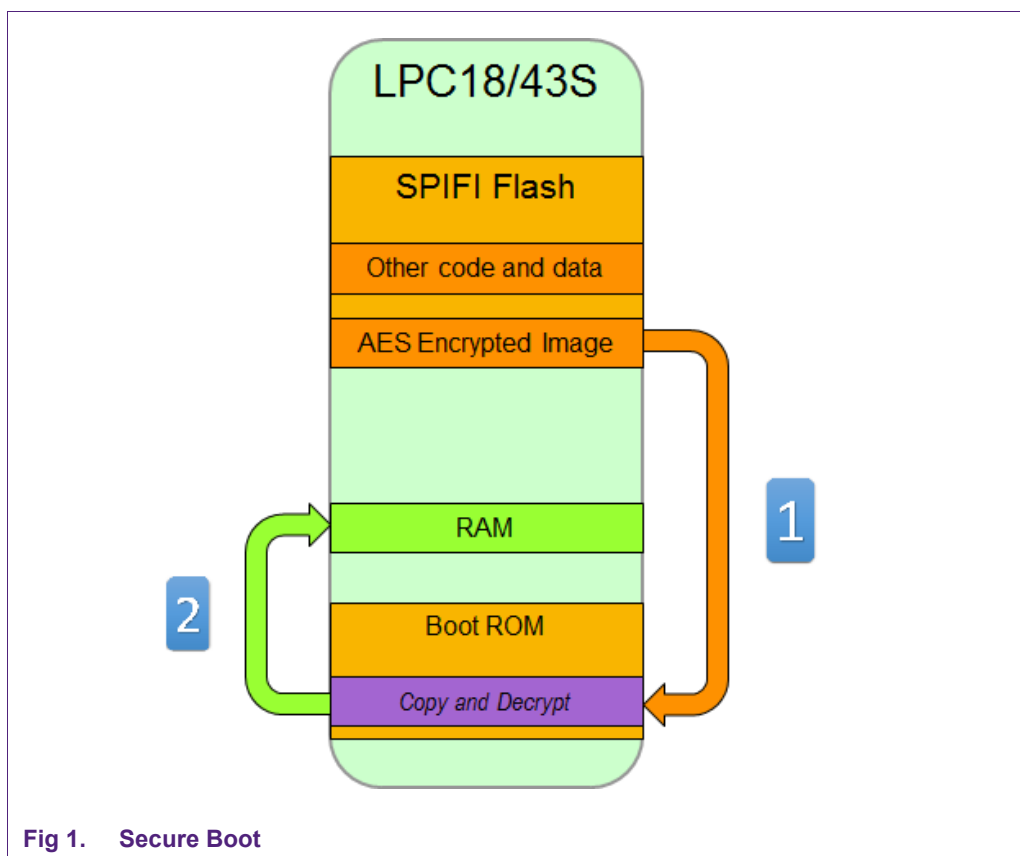
This application note describes the secure boot process from an encrypted image in a quad SPI device (QSPI). For convenience, an example plain binary image 'periph_blinky.bin' and its encrypted image 'encrypted_blinky.bin.hdr' are provided with this application note. Various other software examples are available in the LPCOpen package:

<http://www.lpcware.com/content/nxpfile/lpcopen-software-development-platform-lpc43xx-packages>

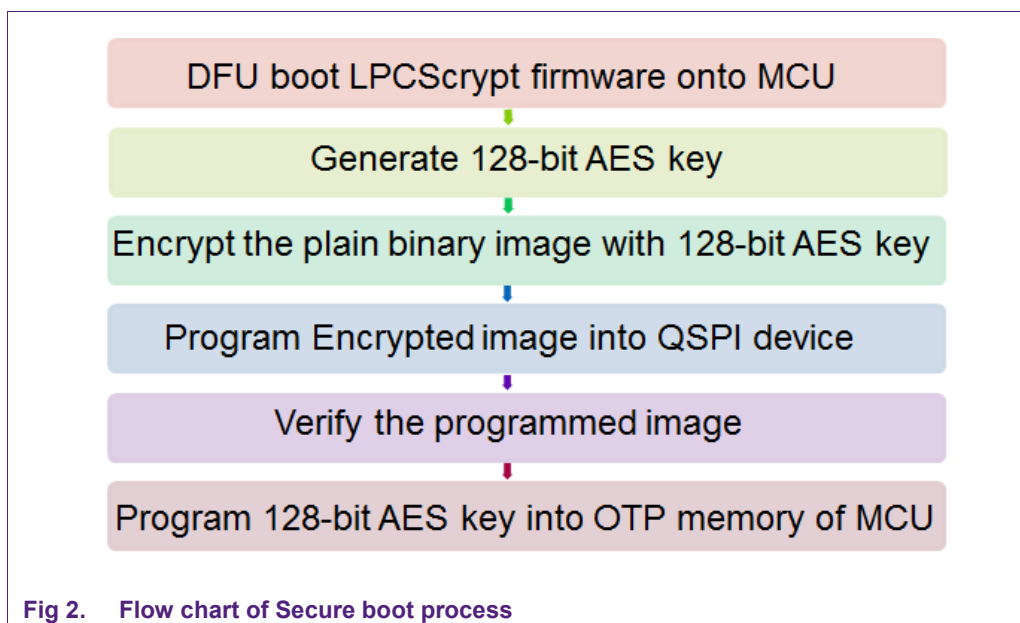
2. Secure Boot Flow

[Fig 1](#) shows the two-step process involved in secure booting from an encrypted image.

1. The encrypted image present in the QSPI device is read by the boot rom and decrypted using the AES key in OTP memory.
2. The decrypted image is placed in internal RAM and is executed.



[Fig 2](#) shows the various steps involved in creating the encrypted image and programming it into the QSPI device.



3. Hardware Setup

The LPC43S37 LPCXpresso V3 board (OM # 13073) is used in this application note. The board can be ordered from the following link:

<http://www.nxp.com/demoboard/OM13073.html>

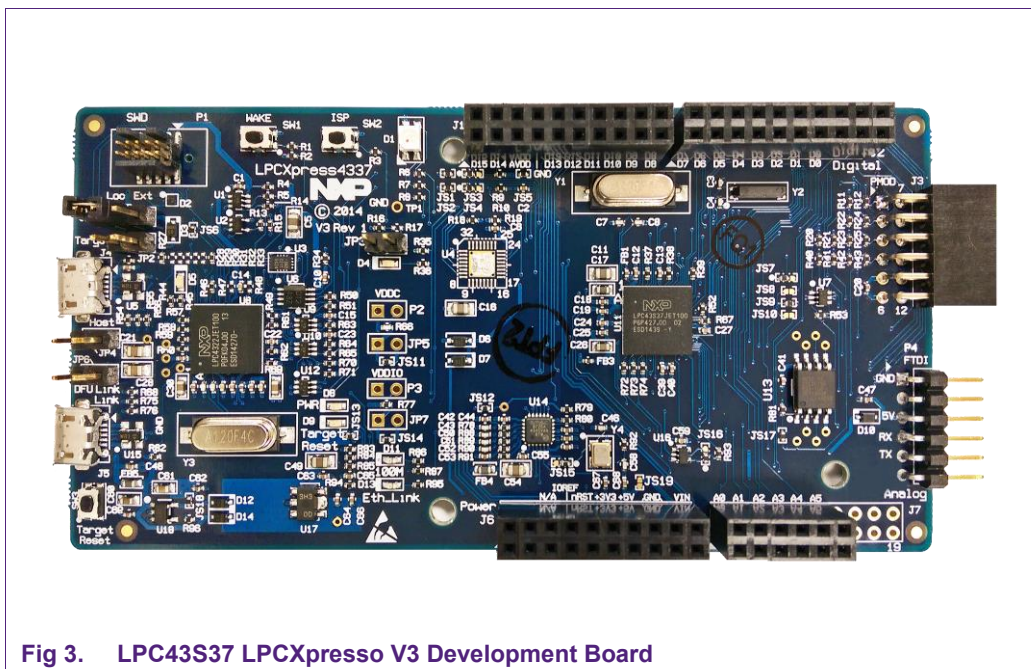


Fig 3. LPC43S37 LPCXpresso V3 Development Board

4. Creating a plain binary image

Download the LPCOpen software package for LPCXpresso V3 board from the following website:

<http://www.lpcware.com/content/nxpfile/lpcopen-software-development-platform-lpc43xx-packages>

Any binary image designed for secure booting must be linked to run from RAM at 0x10000000. The image size should be set to no more than the size of the SRAM located at 0x1000 0000. This is essential since the image will be decoded and copied into RAM before execution.

4.1 Creating a binary image in LPCXpresso IDE

In LPCXpresso, select Project -> Properties -> MCU settings and change the target memory address to RAM as shown in [Fig 4](#).

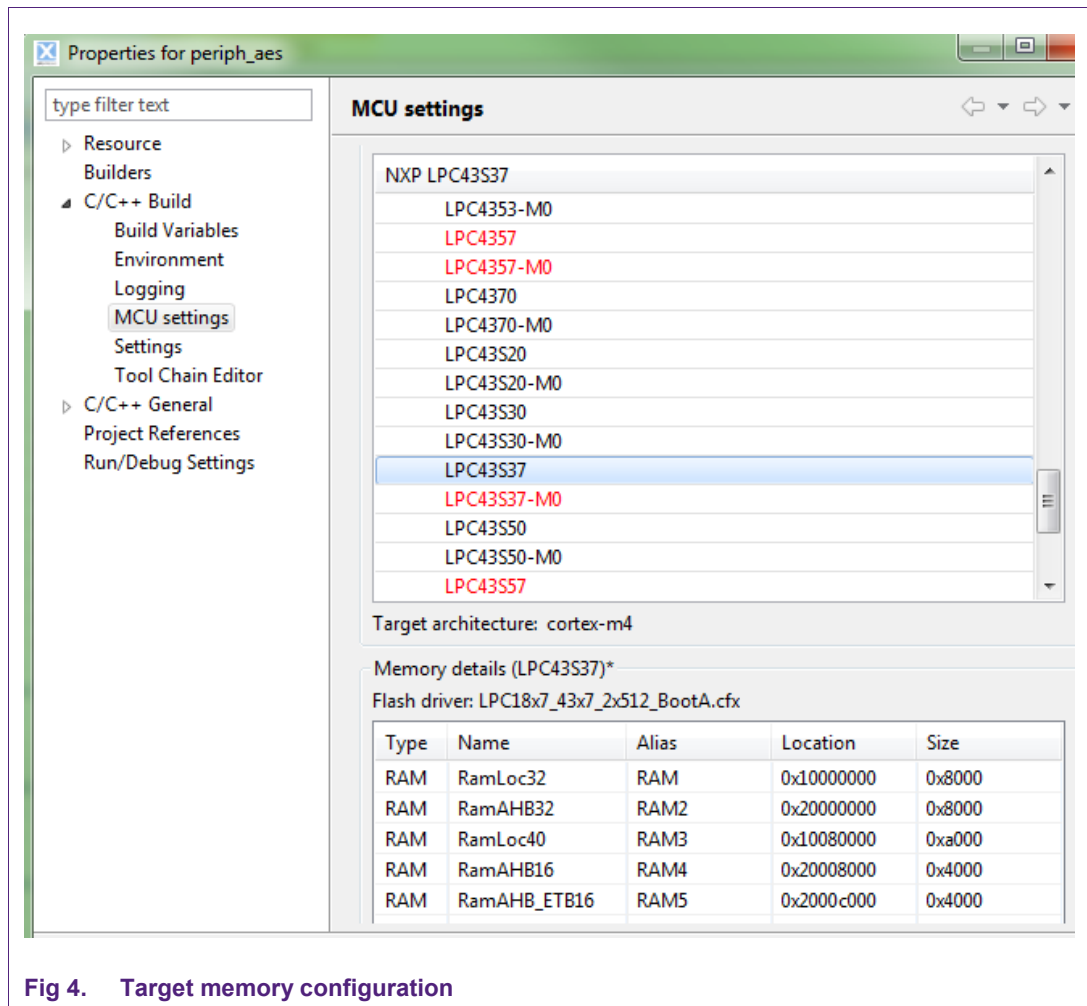


Fig 4. Target memory configuration

To create the binary file, select the .axf file in the Project Explorer, right-click and select "Binary Utilities->Create binary". See [Fig 5](#).

For more information on how to create a binary file in LPCXpresso IDE, go to:

<http://www.lpcware.com/content/faq/lpcxpresso/generating-srec-binary-and-ihex-files>

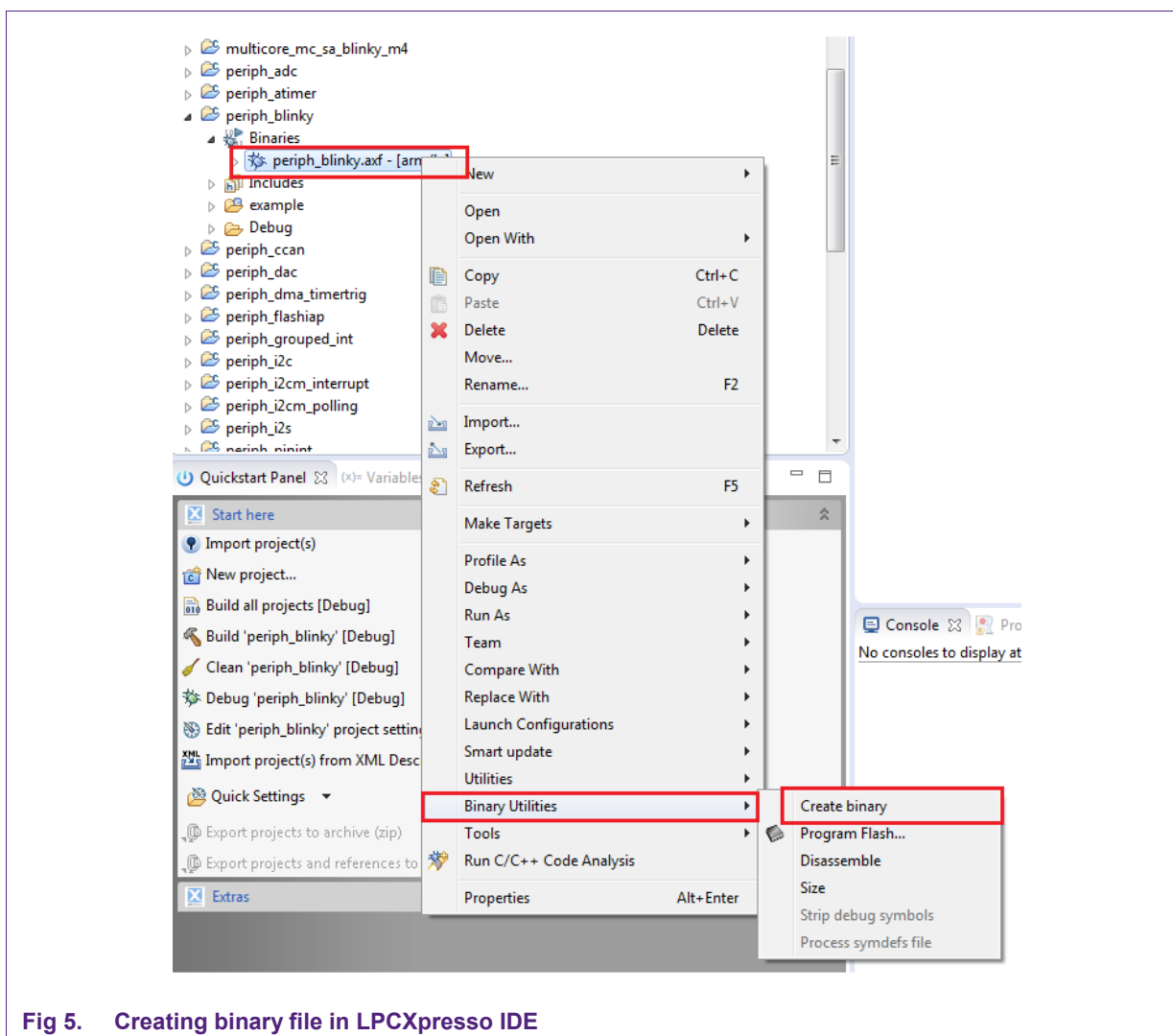


Fig 5. Creating binary file in LPCXpresso IDE

4.2 Creating a binary image in Keil MDK Tool chain

Select the active project. Click on the 'Options for target' icon to configure the target options.

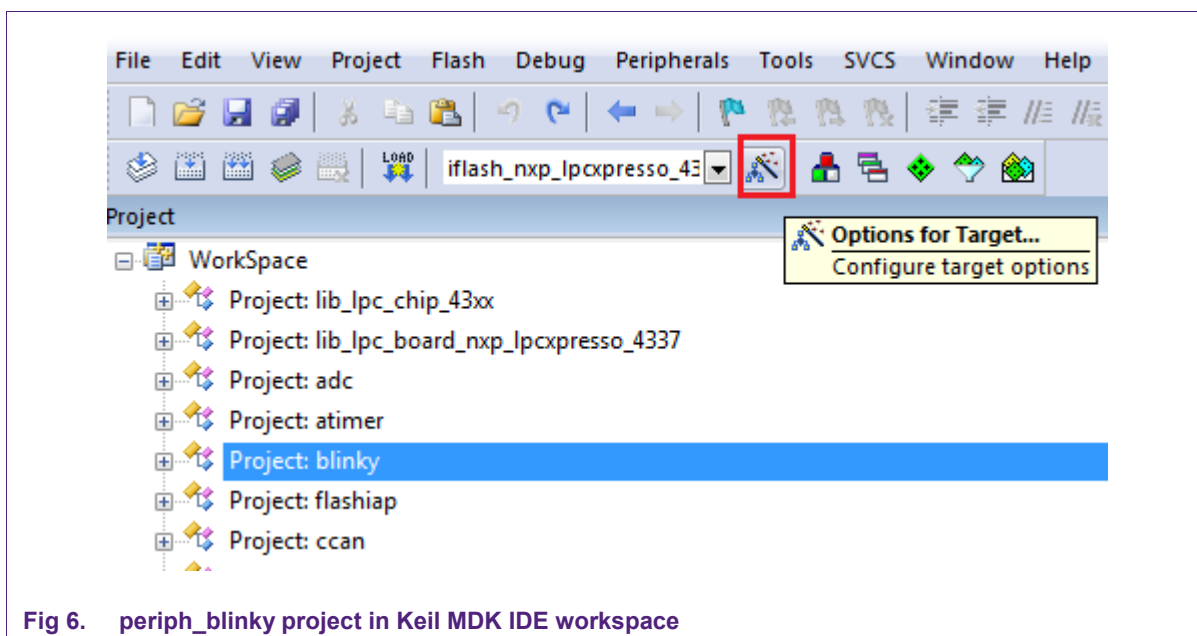


Fig 6. periph_blinky project in Keil MDK IDE workspace

Change the target memory configuration to RAM. See [Fig 7](#).

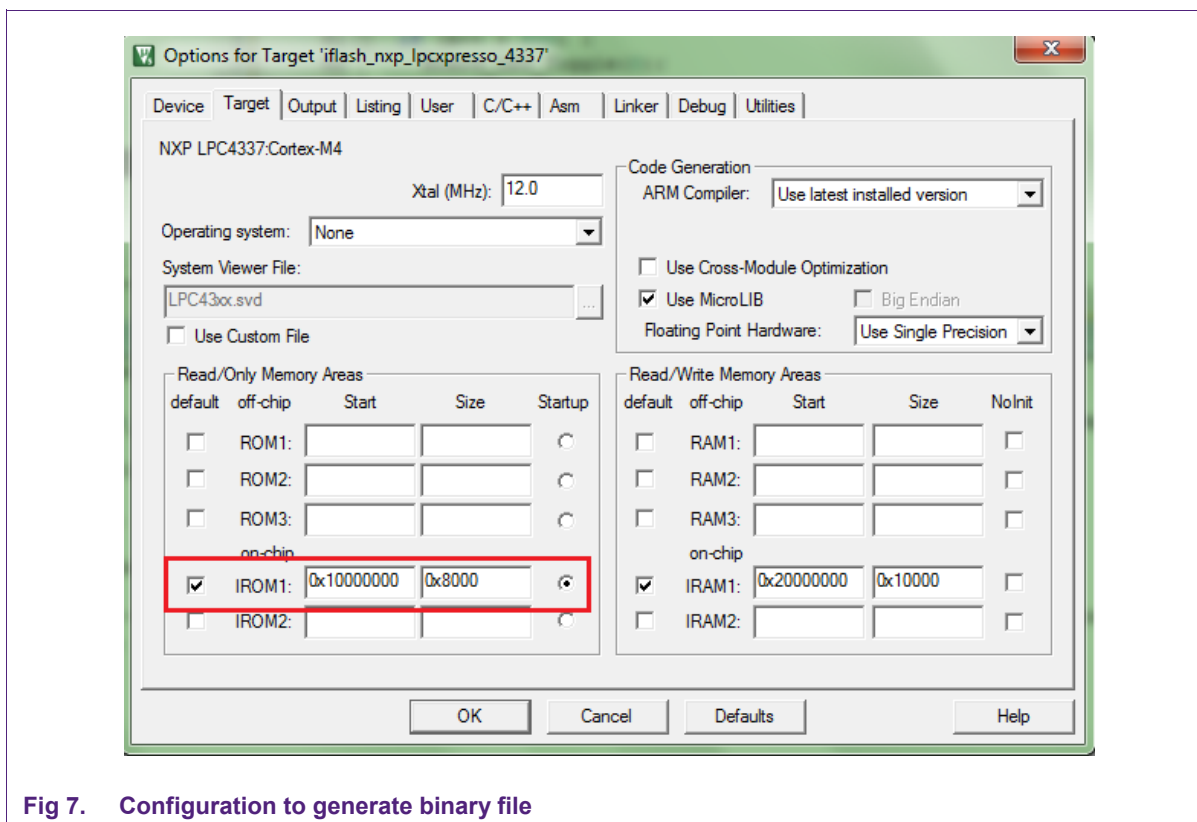


Fig 7. Configuration to generate binary file

In the 'User' tab, enter the command **fromelf --bin -o "\$L@L.bin" "\$L@L.axf"** in Run #2 field and select the check box for generating a binary file from axf file. See [Fig 8](#).

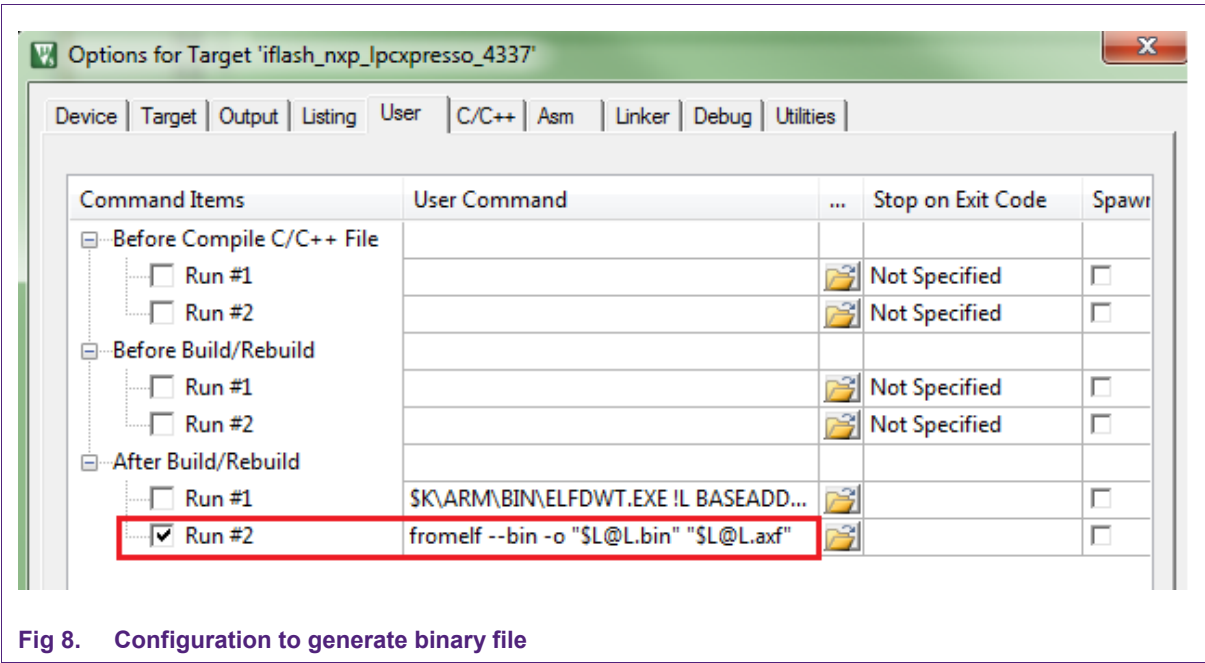


Fig 8. Configuration to generate binary file

4.3 Creating a binary image in IAR Workbench

In IAR Workbench, go to Project -> Options -> Linker and edit the memory configuration in the .icf file. See Fig 9. Then, go to Project -> Options -> Output Converter. Change the output format to 'binary' and select the checkbox .

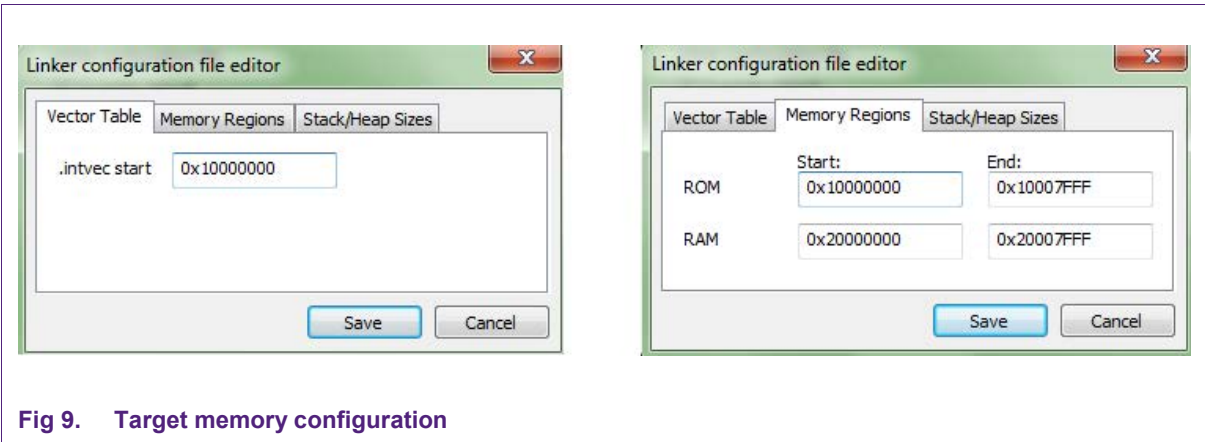


Fig 9. Target memory configuration

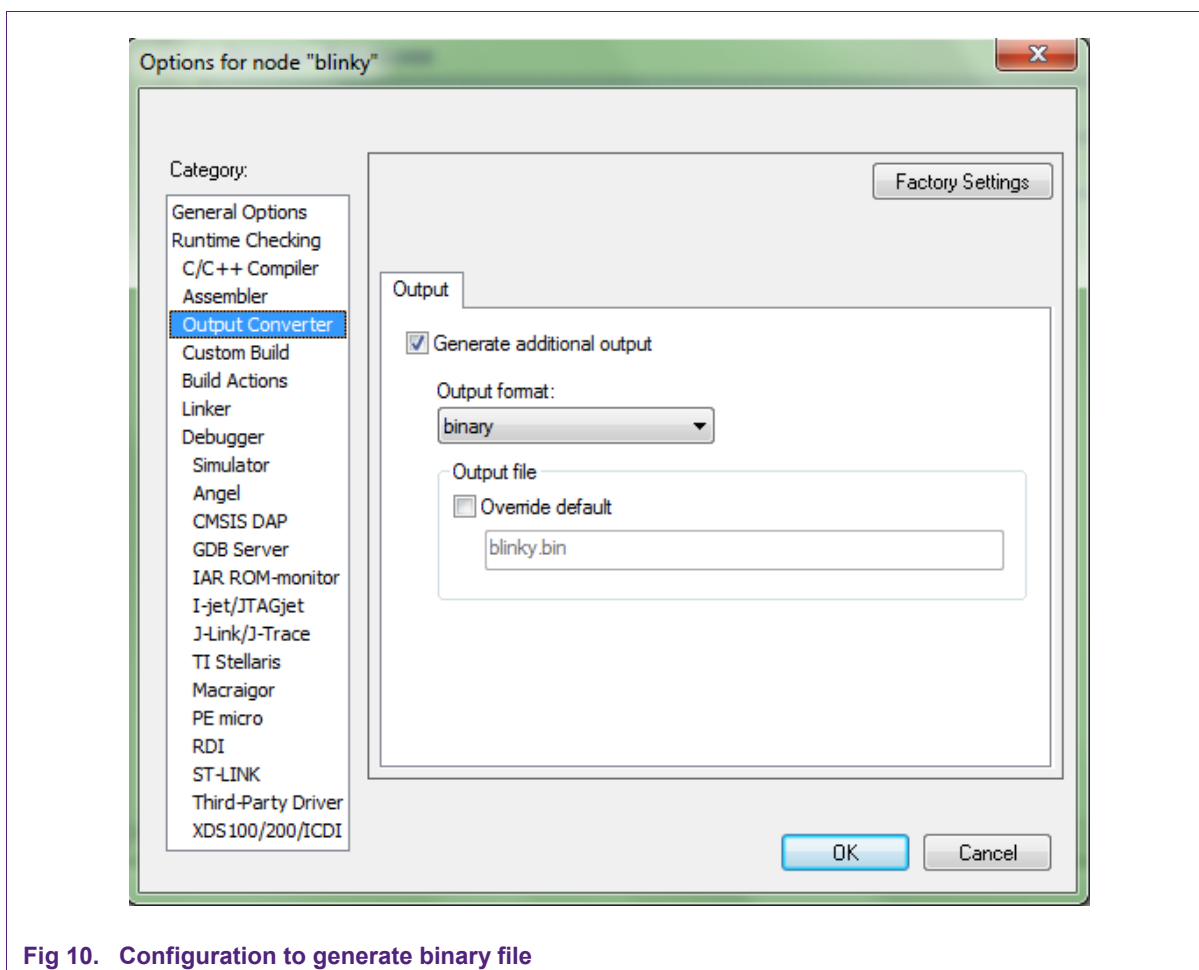


Fig 10. Configuration to generate binary file

5. Creating an encrypted image

An encrypted image can be created from a plain image using the image manager utility integrated into the LPCScript tool.

The image manager utility provides two main functions:

- Adds a standard header information to a binary file required for either a DFU or a Secure boot operation from SPIFI Flash in LPC18Sxx/43Sxx devices.
- Encrypts a binary file using a supplied AES key.

In the Developer mode an all 0 AES key is used to encrypt an image for testing purposes. The default AES key in the MCU is all 0. During debug, it is recommended to use this default key. **Do not program 0s into OTP memory. Programming 0s will block JTAG access for flashless parts.**

To create an encrypted binary image, open the command prompt on the PC and navigate to the bin sub-directory - `lpcscript_aes\bin`.

The syntax to create an encrypted image is:

```
image_manager -key <AES Key> --i <path to binary>
```

```
-o <path to binary.hdr> --bin
```

Enter the following command in the terminal to convert a plain image 'periph_blinky.bin' to an encrypted image with a header 'encrypted_blinky.bin.hdr' using AES key 00000000000000000000000000000000.

```
C:\LPCScript\lpcscript_aes\bin>image_manager -key  
00000000000000000000000000000000 --i ..\images\periph_blinky.bin  
-o ..\images\encrypted_blinky.bin.hdr -bin
```

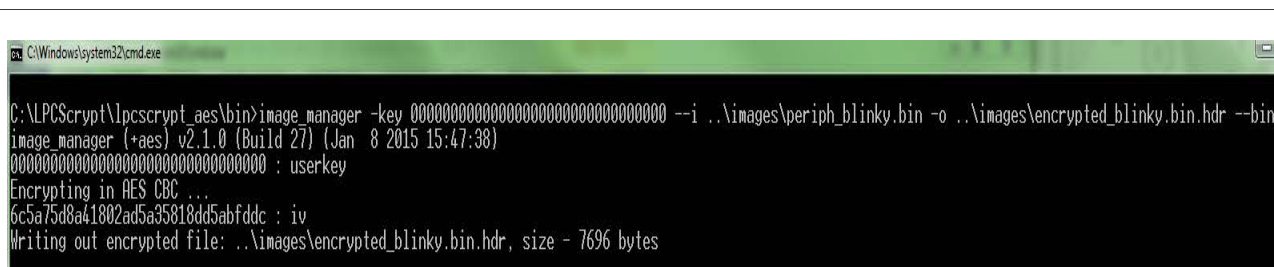


Fig 11. Configuration to generate binary file

This command invokes the image manager utility and uses a 128 bit AES key (all 0). The input binary file 'periph_blinky.bin' is present in a folder named 'images' and the output binary file with header 'encrypted_blinky.bin.hdr' is generated in the same 'images' folder.

Cipher-Block Chaining (CBC) mode of encryption is used to create the encrypted image.

6. Programming an Encrypted Image

The encrypted image can be programmed into the QSPI device using the LPCScript tool.

Due to export control regulations, support for creating AES keys and secure images is not included in some versions of LPCScript. Contact your supplier for details on obtaining a version of LPCScript that supports these features. For more information on this tool, visit: <http://www.lpcware.com/LPCScript>

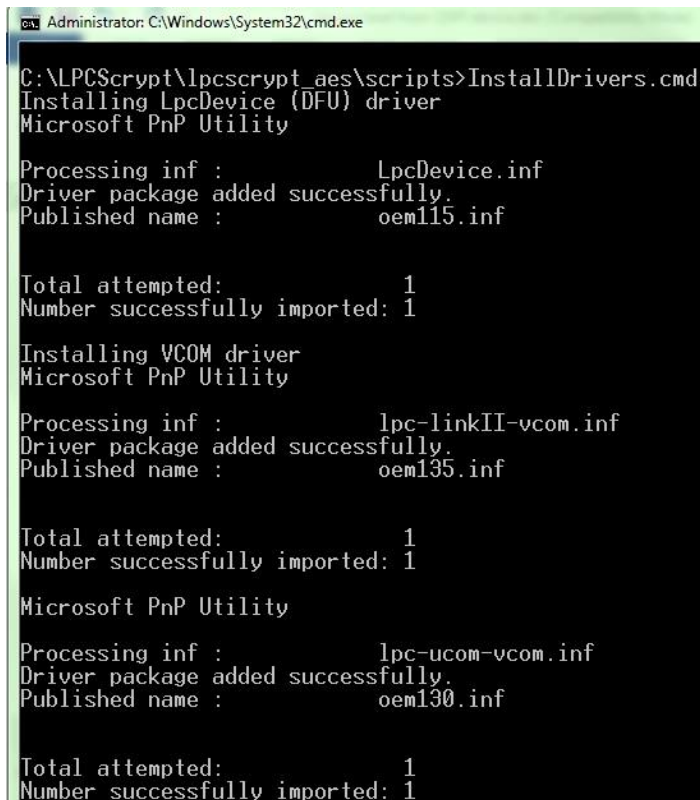
LPCScript consists of two parts, a multi-platform command line tool and an MCU firmware monitor. The firmware monitor is downloaded to the target MCU using USB DFU support built into the on-chip ROM (using USB0). The firmware creates a virtual serial port (VCOM) over USB0 to communicate with the host.

The LPCScript host tool provides a command-line interface to the firmware, giving access to the programmable features of the MCU. It can be invoked with a single command or a script file containing a sequence of commands.

6.1 Driver Installation

Open the command prompt as an **administrator** on the PC and navigate to the scripts sub-directory - `lpcscript_aes\scripts`.

Enter 'InstallDrivers.cmd' command to install the required drivers. See [Fig 12](#).



```
Administrator: C:\Windows\System32\cmd.exe

C:\LPCScript\lpcscript_aes\scripts>InstallDrivers.cmd
Installing LpcDevice (DFU) driver
Microsoft PnP Utility

Processing inf :          LpcDevice.inf
Driver package added successfully.
Published name :          oem115.inf

Total attempted:          1
Number successfully imported: 1

Installing VCOM driver
Microsoft PnP Utility

Processing inf :          lpc-linkII-vcom.inf
Driver package added successfully.
Published name :          oem135.inf

Total attempted:          1
Number successfully imported: 1

Microsoft PnP Utility

Processing inf :          lpc-ucom-vcom.inf
Driver package added successfully.
Published name :          oem130.inf

Total attempted:          1
Number successfully imported: 1
```

Fig 12. Driver installation

6.2 Booting LPCScript Firmware

On LPC43S37 LPCXpresso V3 board, connect a micro-USB cable into J4 connector and leave JP3 open. By default, the boot pins are set to boot from USB0. For flash devices, the ISP mode is entered to boot LPCScript when flash is blank.

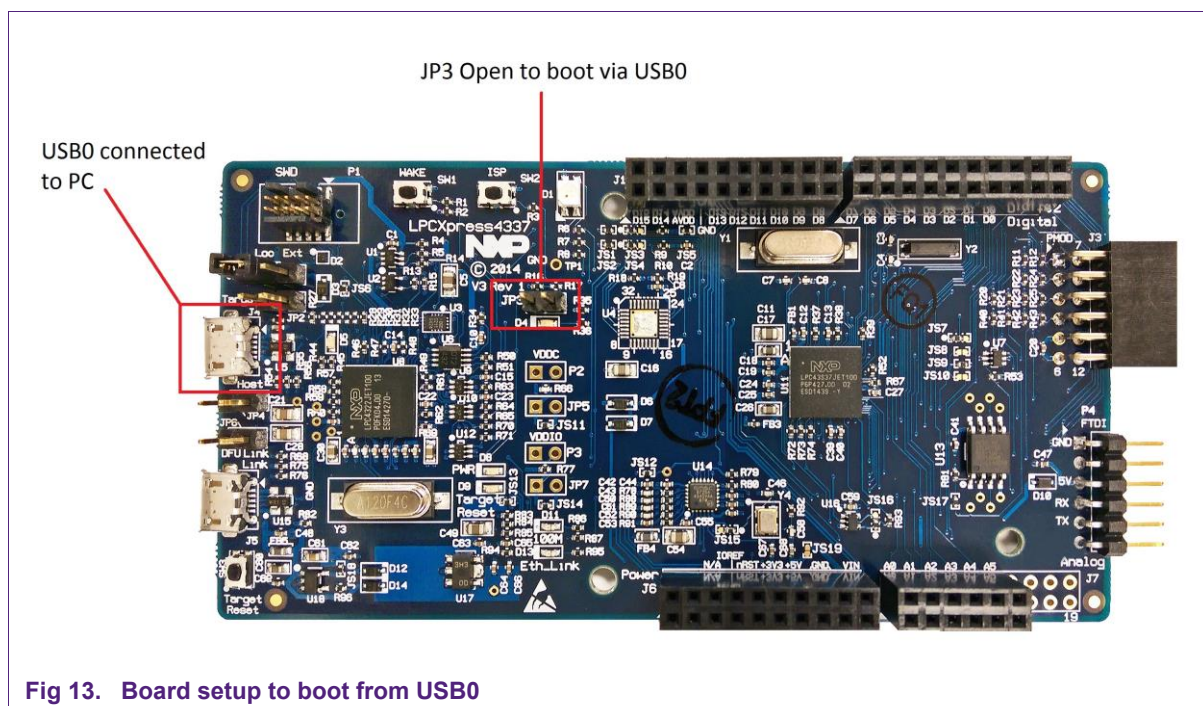


Fig 13. Board setup to boot from USB0

In the scripts sub-directory, enter the command 'boot_lpcscript.cmd' in the terminal. This command downloads LPCScript firmware image into Internal RAM of target MCU and boots the image via USB0.

```
C:\LPCScript\lpcscript_aes\scripts>boot_lpcscript.cmd
Booting LPCScript target with "LPCScript_53.bin.hdr"
LPCScript target booted
```

Fig 14. Boot LPCScript Firmware

6.3 Program encrypted image

Navigate to the bin sub-directory - lpcscript_aes\bin.

The syntax to program and verify an image in a QSPI device is:

```
lpcscript program <path to binary.hdr> SPIFI
```

```
lpcscript verify <path to binary.hdr> SPIFI
```

Enter the commands, shown in [Fig 15](#) to program 'encrypted_blinky.bin.hdr' into QSPI device.

```
C:\LPCScript\lpcscript_aes\bin>lpcscript program ..\images\encrypted_blinky.bin.hdr SPIFI
Programmed 7696 bytes to 0x14000000 in 0.484s (15.541KB/sec)
C:\LPCScript\lpcscript_aes\bin>lpcscript verify ..\images\encrypted_blinky.bin.hdr SPIFI
Verified 7696 bytes to 0x14000000 in 0.062s (120.441KB/sec)
```

Fig 15. Programming an image

6.4 Program AES keys into OTP Memory

The same key that is used for encrypting the plain binary image must be programmed into the OTP memory bank. When booting from SPIFI, the boot code checks the AES key stored in the OTP memory, decrypts the image using this key, and places the decrypted image in internal RAM.

Note: The AES keys can be programmed only one time and once programmed JTAG is disabled for flashless parts. No further debug operations are possible with the device. Test the application many times in Developer mode (128-bit all 0 AES key) before programming the AES key.

The syntax for programming the AES keys in OTP is:

```
1pcscrypt aesProgramKey1 <AES Key1>
```

```
1pcscrypt aesProgramKey2 <AES Key2>
```

To secure boot the encrypted image from QSPI device, close the JP3 header jumper and press reset. The red LED on the LPCXpresso V3 board will blink.

7. Conclusion

Secure boot ensures security of the code or IP when booting from external memory. The image is encrypted in the QSPI flash and therefore, the code is unintelligible even if read by an unauthorized user. The decryption is done dynamically by boot code and hence eavesdropping is prevented at all stages of boot and execution. Once the AES keys are programmed in OTP memory, JTAG access is blocked in flashless parts and further debugging is made impossible. This provides added code protection.

The decrypted image is placed in internal RAM, which speeds up program execution.

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